Power MOSFET –30V, 98mΩ, –3.5A, Single P-Channel

This Power MOSFET is produced using ON Semiconductor's trench technology, which is specifically designed to minimize gate charge and low on resistance. This device is suitable for applications with low gate charge driving or low on resistance requirements.

Features

- Low On-Resistance
- 4V drive
- Pb-Free, Halogen Free and RoHS compliance
- Ultra small package MCPH6 (2.0mm×2.1mm×0.85mmt)

Typical Applications

• Load Switch

SPECIFICATIONS

ABSOLUTE MAXIMUM RATING at Ta = 25°C (Note 1, 2)

Parameter	Symbol	Value	Unit
Drain to Source Voltage	VDSS	-30	V
Gate to Source Voltage	VGSS	±20	V
Drain Current (DC)	ΙD	-3.5	Α
Drain Current (Pulse) PW ≤ 10µs, duty cycle ≤ 1%	IDP	-14	Α
Power Dissipation When mounted on ceramic substrate (1200mm² × 0.8mm)	PD	1.5	W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55 to +150	°C

- Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
 - be assumed, damage may occur and reliability may be affected.

 2: This product is designed to "ESD immunity<200V*", so please take care when handling.
 - *Machine Model

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Value	Unit		
Junction to Ambient					
When mounted on ceramic substrate (1200mm ² × 0.8mm)	$R_{\theta JA}$	83.3	°C/W		

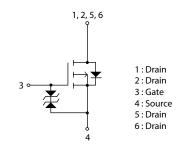


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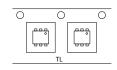
www.onsemi.com

VDSS	R _{DS} (on) Max	ID Max
	98mΩ@ -10V	
-30V	171mΩ@ –4.5V	-3.5A
	199mΩ@ –4V	

ELECTRICAL CONNECTION P-Channel



PACKING TYPE: TL MARKING





ORDERING INFORMATION

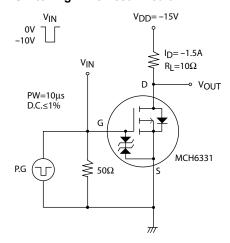
See detailed ordering and shipping information on page 5 of this data sheet.

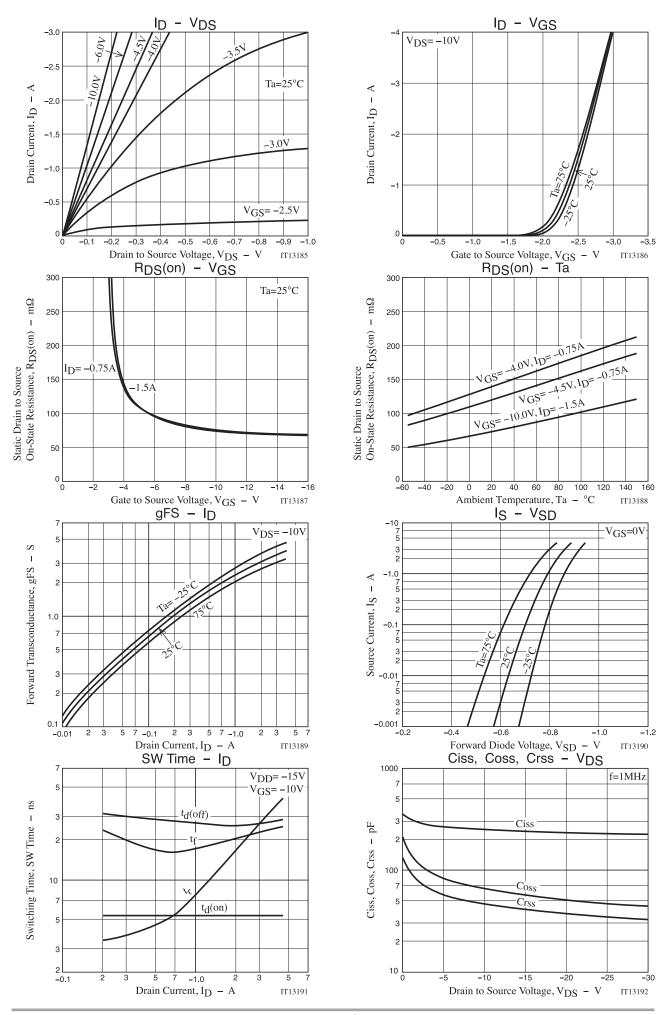
ELECTRICAL CHARACTERISTICS at Ta = 25°C (Note 3)

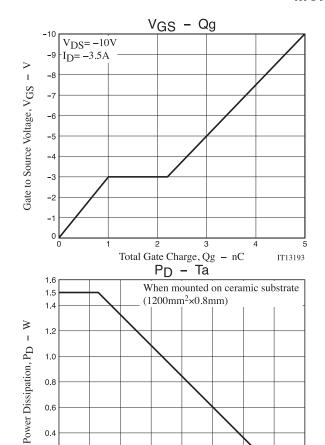
Parameter	Cumbal	Conditions	Value			Unit	
Farameter	Parameter Symbol Conditions		min	typ	max	Offic	
Drain to Source Breakdown Voltage	V(BR)DSS	I _D =-1mA, V _G S=0V	-30			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =-30V, V _{GS} =0V			-1	μΑ	
Gate to Source Leakage Current	IGSS	V _{GS} =±16V, V _{DS} =0V			±10	μΑ	
Gate Threshold Voltage	V _{GS} (th)	V _{DS} =-10V, I _D =-1mA	-1.2		-2.6	V	
Forward Transconductance	gFS	V _{DS} =-10V, I _D =-1.5A		2.8		S	
Static Drain to Source On-State Resistance	R _{DS} (on)1	I _D =-1.5A, V _G S=-10V		75	98	$m\Omega$	
	R _{DS} (on)2	I _D =-0.75A, V _G S=-4.5V		122	171	$m\Omega$	
	R _{DS} (on)3	I _D =-0.75A, V _G S=-4V		142	199	$m\Omega$	
Input Capacitance	Ciss			250		pF	
Output Capacitance	Coss	V _{DS} =–10V, f=1MHz		65		pF	
Reverse Transfer Capacitance	Crss			46		pF	
Turn-ON Delay Time	t _d (on)			5.4		ns	
Rise Time	tr	Can appoint Toot Circuit		12		ns	
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit		26		ns	
Fall Time	tf			19		ns	
Total Gate Charge	Qg			5.0	·	nC	
Gate to Source Charge	Qgs	V _{DS} =-10V, V _{GS} =-10V, I _D =-3.5A		1.0		nC	
Gate to Drain "Miller" Charge	Qgd			1.2		nC	
Forward Diode Voltage	V _{SD}	I _S =-3.5A, V _{GS} =0V		-0.86	-1.5	V	

Note 3 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

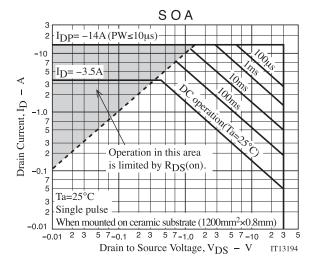
Switching Time Test Circuit

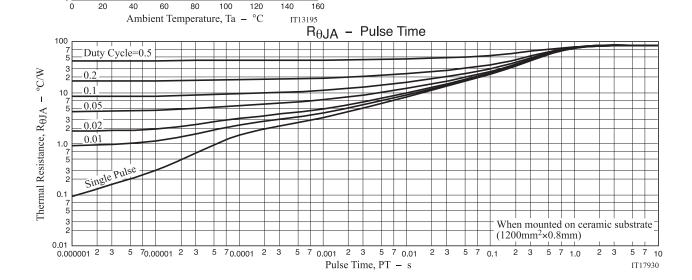






0.6 0.4 0.2 0

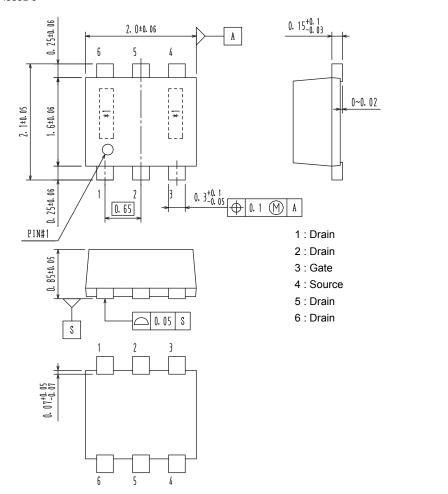




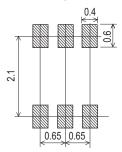
PACKAGE DIMENSIONS

unit : mm

SC-88FL / MCPH6 CASE 419AS ISSUE O



Recommended Soldering Footprint



ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing)	
MCH6331-TL-H	YF	SC-88FL / MCPH6	3,000 / Tape & Reel	
MCH6331-TL-W	TF	(Pb-Free / Halogen Free)		

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

Note on usage: Since the MCH6331 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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